



DXTP03060CFG

60V PNP LOW VCESAT TRANSISTOR IN PowerDI3333-8

Features

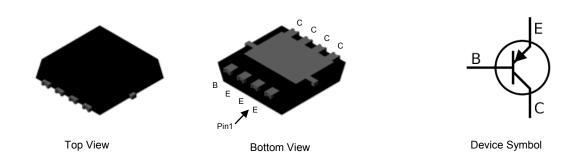
- BV_{CEO} > -60V
- Small Form Factor Thermally Efficient Package. Enables Higher Density End Products
- I_c = -5.5A Continuous Collector Current
- I_{CM} = -15A Peak Pulse Current
- Low Saturation Voltage V_{CE(sat)} < 90mV @ -1A
- h_{FE} Specified Up to -10A for a High Gain Hold Up
- Complementary NPN Type: DXTN03060CFG
- Rated to +175°C Ideal For High Temperature Environment
- Wettable Flank For Improved Optical Inspection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: PowerDI[®]3333-8
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—Matte Tin Plated Leads Solderable per MIL-STD-202, Method 208 ⁽²⁾
- Weight: 0.03 grams (Approximate)

Applications

- Motor Driving
- Line Switching
- High Side Switches



Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DXTP03060CFG-7	2J8	7	12	2000

No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

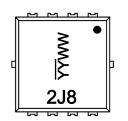
4. For packaging details, go to our website at https://www.diodes.com/products/packages.html.

PowerDI3333-8 (SWP) (Type UX)

Marking Information

Notes:

PowerDI3333-8 (SWP) (Type UX)



2J8= Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 19 = 2019) WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-70	V
Collector-Emitter Voltage	V _{CEO}	-60	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	I _C	-5.5	A
Peak Pulse Current	I _{CM}	-15	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
	(Note 5)		1.07	W
Power Dissipation	(Note 6)	PD	2.3	W
	(Note 7)		3.4	W
	(Note 5)		140	°C/W
Thermal Resistance, Junction to Ambient	(Note 6)	R _{0JA}	65	°C/W
	(Note 7)		44	°C/W
Thermal Resistance, Junction to Leads (Note 8)		R _{OJL}	6	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C	

ESD Ratings (Note 9)

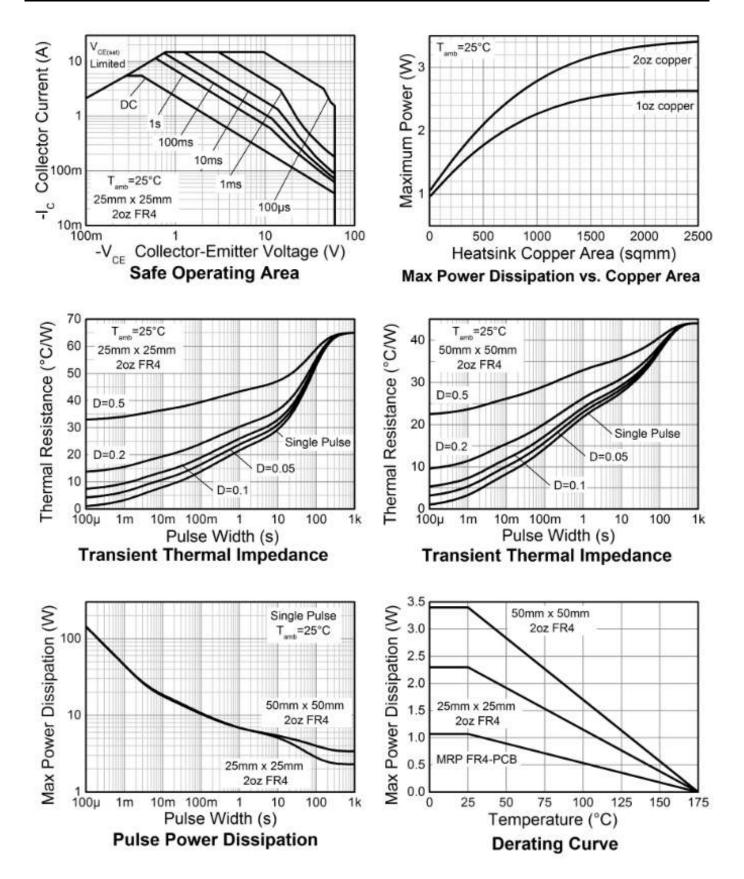
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4000	V	ЗA
Electrostatic Discharge - Machine Model	ESD MM	≥ 400	V	С

 For a device mounted with the collector tab on MRP FR4-PCB; device is measured under still air conditions whilst operating in a steady-state.
Same as Note 5, except the device is mounted on 25mm × 25mm 2oz copper.
Same as Note 5, except the device is mounted on 50mm × 50mm 2oz copper. Notes:

Thermal resistance from junction to solder-point (at the collector tab).
Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristics and Derating Information





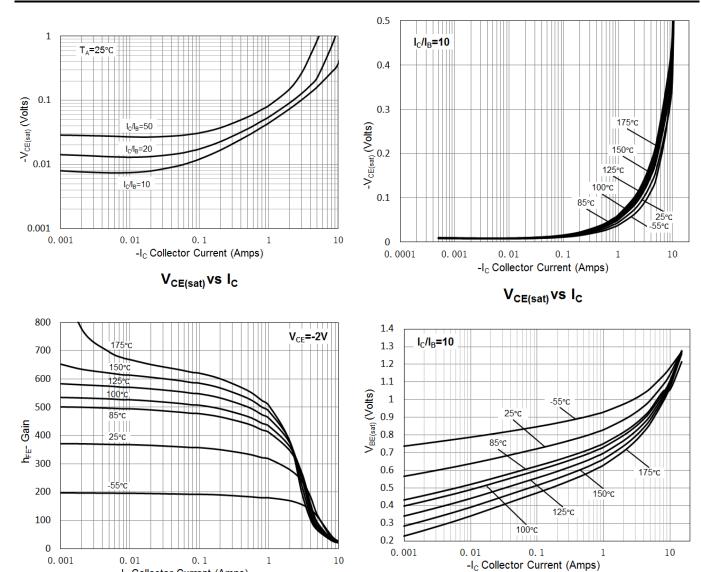
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Мах	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-70	-102	_	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 10)	BV _{CEO}	-60	-79	_	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.6	_	V	I _E = -100μA
Collector-Base Cutoff Current	I _{CBO}	_	-1	-50	nA	V _{CB} = -70V
Collector-Base Cuton Current			-0.06	-10	μA	V _{CB} = -70V, T _A = +125°C
	I _{CER}		-1	-50	nA	V _{CB} = -60V
Collector-Emitter Cutoff Current	R ≤ 1kΩ		-1	-10	μA	V _{CB} = -60V, T _A = +125°C
Emitter Cutoff Current	I _{EBO}		-1	-20	nA	V _{EB} = -6V
		240	362	_		I _C = -10mA, V _{CE} = -2V
Otatia Farmani Ormani Transfer Datia (Nata 40)	h _{FE}	200	308	800		I _C = -1A, V _{CE} = -2V
Static Forward Current Transfer Ratio (Note 10)		180	271	_		$I_{\rm C}$ = -2A, $V_{\rm CE}$ = -2V
		45	130	_		I _C = -5A, V _{CE} = -2V
			-12	-30	mV	I _C = -100mA, I _B = -10mA
	V _{CE(sat)}		-44	-90	mV	I _C = -1A, I _B = -100mA
Collector-Emitter Saturation Voltage (Note 10)			-74	-150	mV	I _C = -2A, I _B = -200mA
			-161	-300	mV	I _C = -5A, I _B = -500mA
Base-Emitter Saturation Voltage (Note 10)	V _{BE(sat)}		-995	-1.1	V	I _C = -5A, I _B = -500mV
Base-Emitter Turn-On Voltage (Note 10)	V _{BE(on)}		-891	-1	V	I _C = -5A, V _{CE} = -1V
Output Capacitance	C _{obo}	_	48	_	pF	V _{CB} = -10V. f = 1MHz
Transition Frequency	f _T	_	120	_	MHz	V _{CE} = -10V, I _C = -100mA f = 50MHz
	t _{delay}		5		ns	
	t _{rise}		300		ns	V _{CC} = -10V, I _C = -1A
Switching Characteristics	t _{storage}	—	1486	—	ns	$I_{B1} = -I_{B2} = -100 \text{mA}$
	t _{fall}	_	191	_	ns	7

Note: 10. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.

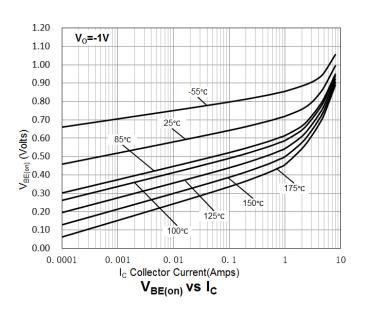


Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)





-I_C Collector Current (Amps)



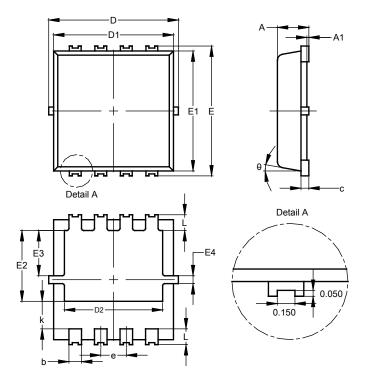
 $V_{\text{BE(sat)}} \, vs \, \, I_{\text{C}}$



Package Outline Dimensions

Please see https://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (SWP) (Type UX)

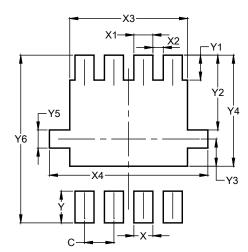


PowerDI3333-8 (SWP)						
	(Type UX)					
Dim	Min	Мах	Тур			
Α	0.75	0.85	0.80			
A1	0.00	0.05				
b	0.25	0.40	0.32			
С	0.10	0.25	0.15			
D	3.20	3.40	3.30			
D1	2.95	3.15	3.05			
D2	2.30	2.70	2.50			
Е	3.20	3.40	3.30			
E1	2.95	3.15	3.05			
E2	1.60	2.00	1.80			
E3	0.95	1.35	1.15			
E4	0.10	0.30	0.20			
е		_	0.65			
k	0.50	0.90	0.70			
L	0.30	0.50	0.40			
θ	0°	12°	10°			
All [All Dimensions in mm					

Suggested Pad Layout

Please see https://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (SWP) (Type UX)



Dimensions	Value (in mm)
С	0.650
Х	0.420
X1	0.420
X2	0.230
X3	2.600
X4	3.500
Y	0.700
Y1	0.550
Y2	1.650
Y3	0.600
Y4	2.450
Y5	0.400
Y6	3.700

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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